<u>S/N 10/774,869</u> <u>PATENT</u>

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Song-Hua Shi et al. Examiner: Jennifer Matisiak Serial No.: 10/774,869 Group Art Unit: 2811 Filed: February 9, 2004 Docket No.: 884.698US2

Title: UNDERFILL PROCESS FOR FLIP-CHIP

DEVICE

Customer Number: 21186

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

MS Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

This responds to the Office Action mailed on April 21, 2006. Please amend the aboveidentified patent application as follows.